

Title (en)

Composition for treating copper or copper alloys

Title (de)

Zusammensetzung für die Behandlung von Kupfer oder Kupferlegierungen

Title (fr)

Composition pour le traitement de cuivre ou des alliages de cuivre

Publication

EP 0620293 B1 19970115 (EN)

Application

EP 94105065 A 19940330

Priority

JP 10012193 A 19930405

Abstract (en)

[origin: EP0620293A1] A composition suitable for the treatment of surfaces of copper and copper alloys is disclosed. It comprises, (a) a cupric complex of an azole compound, (b) an organic acid having a boiling point or a decomposition point of 230 DEG C or lower, (c) a difficultly volatile complexing agent, (d) a complexing agent having a complexing power which is weaker than that of the azole compound, and (e) water. The treatment of copper or copper alloys with the composition produces abraded surface with moderate irregularities, thereby ensuring better adhesion of various resists thereto and increased solderability. The composition is particularly useful for the manufacture of printed-wiring boards.

IPC 1-7

C23F 1/18

IPC 8 full level

C23F 1/18 (2006.01); **B23K 35/36** (2006.01); **C23F 1/14** (2006.01); **H05K 3/06** (2006.01); **H05K 3/28** (2006.01); **H05K 3/38** (2006.01)

CPC (source: EP US)

B23K 35/3618 (2013.01 - EP US); **C23F 1/14** (2013.01 - EP US); **H05K 3/383** (2013.01 - EP US); **H05K 3/064** (2013.01 - EP US); **H05K 3/28** (2013.01 - EP US); **H05K 2203/121** (2013.01 - EP US); **H05K 2203/124** (2013.01 - EP US)

Cited by

KR100714171B1; US7220322B1; EP0926265A1; EP1253813A1; EP1104020A1; SG85736A1; EP0757118A1; US5807493A; EP1509358A4; US7210988B2; US6544436B2; US7189336B2; US6783432B2; US7504018B2; US6284309B1; US6579591B2; US6602440B2; US6432826B1; US7104267B2; US6666987B1; US6902626B2

Designated contracting state (EPC)

BE DE FR GB

DOCDB simple family (publication)

EP 0620293 A1 19941019; EP 0620293 B1 19970115; CN 1053233 C 20000607; CN 1120077 A 19960410; DE 69401453 D1 19970227; DE 69401453 T2 19970430; JP H06287774 A 19941011; SG 47858 A1 19980417; TW 256856 B 19950911; US 5439783 A 19950808

DOCDB simple family (application)

EP 94105065 A 19940330; CN 94104029 A 19940404; DE 69401453 T 19940330; JP 10012193 A 19930405; SG 1996004756 A 19940330; TW 82109858 A 19931123; US 21763894 A 19940325